



Product Change Notification / NTDO-15NRSF861

Date:

26-Sep-2021

Product Category:

E-Fuse

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4780 Initial Notice: Qualification of UAT as an additional Cu Pillar bumping site for Microsemi LX8237ILQ-TR, LX8237ILQ-TR-V2R3 and LX8237ILQ-TR-V3R2 catalog part numbers (CPN) available in 24L VQFN (3.5x4.5x1.0mm) package

Affected CPNs:

[NTDO-15NRSF861_Affected_CPN_09262021.pdf](#)

[NTDO-15NRSF861_Affected_CPN_09262021.csv](#)

Notification Text:

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of UAT as an additional Cu Pillar bumping site for Microsemi LX8237ILQ-TR, LX8237ILQ-TR-V2R3 and LX8237ILQ-TR-V3R2 catalog part numbers (CPN) available in 24L VQFN (3.5x4.5x1.0mm) package

Pre and Post Change Summary:

	Pre Change	Post Change
--	------------	-------------

Cu Pillar Bumping location	Unisem Chengdu Co.,Ltd. (UNIC)	Unisem Chengdu Co.,Ltd. (UNIC)	Unisem Advance Tech (UAT)
Bump Material	CuSn	CuSn	CuSn
Bump Diameter	100um	100um	100um

Impacts to Data Sheet:

None

Change Impact:None

Reason for Change:To improve productivity by qualifying UAT as an additional Cu pillar bumping site.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:December 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	September 2021					->	December 2021				
Workweek	3 6	3 7	3 8	3 9	4 0		4 9	5 0	5 1	52	53
Initial PCN Issue Date					X						
Qual Report Availability							X				
Final PCN issue date							X				

Method to Identify Change:

Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:September 26, 2021: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_NTDO-15NRSF861_Qual_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to [receive Microchip PCNs via email](#) please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to [change your PCN profile, including opt out](#), please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

NTDO-15NRSF861 - CCB 4780 Initial Notice: Qualification of UAT as an additional Cu Pillar bumping site for Microsemi LX8237ILQ-TR, LX8237ILQ-TR-V2R3 and LX8237ILQ-TR-V3R2 catalog part numbers (CPN) available in 24L VQFN (3.5x4.5x1.0mm) package

Affected Catalog Part Numbers (CPN)

LX8237ILQ-TR

LX8237ILQ-TR-V2R3

LX8237ILQ-TR-V3R2